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PCN# : P294A
Issue Date : Sep. 28, 2012

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the following products.

This is a minor change that has no impact on product quality, reliability, electrical or mechanical performance. Affected products will remain fully compliant to all published specifications. Notification is being made for informational purposes only and there is no approval required. Products incorporating this change may be shipped interchangeably with existing unchanged products.

Please contact your local Customer Quality Engineer if you have any questions regarding this notification. Alternatively, you may send an email request for information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Oct. 15, 2012

Expected First Date Code of Changed Product :4312

Description of Change (From) :
Current wafer fabrication is at Fairchild Semiconductor Fairchild Semiconductor Salt Lake, Utah and Taiwan Semiconductor Manufacturing Company Limited, Taiwan.

Description of Change (To) :
In addition to Fairchild Semiconductor Salt Lake, Utah and Taiwan Semiconductor Manufacturing Company Limited, Taiwan, products will be manufactured at the Fairchild Semiconductor FAB-8 Mountaintop, PA. This facility has been a qualified wafer fabrication site and producing other parts with this same wafer fab process and product family since 2005. Design, die size and layout of the affected products (see affected FSID list) remain unchanged. There are no changes in the datasheet or electrical performance between products manufactured at the Current and Alternate wafer fab locations.

Reason for Change:
Utilization of available capacity of our MTP fab to support our customer base.

Affected Product(s):

FDC655BN	FDC655BN_F123	FDC655BN_G
FDMC8884	FDMC8884_F126	